

BIPOLAR ANALOG INTEGRATED CIRCUIT

μ PC8215TU

SiGe LOW NOISE AMPLIFIER FOR GPS/MOBILE COMMUNICATIONS

DESCRIPTION

The μ PC8215TU is a silicon germanium (SiGe) monolithic integrated circuit designed as low noise amplifier for GPS and mobile communications.

The package is 8-pin lead-less minimold suitable for surface mount.

This IC is manufactured using our 50 GHz fmax UHS2 (Ultra High Speed Process) SiGe bipolar process.

FEATURES

Low noise
 NF = 1.3 dB TYP. @ Vcc = 3.0 V
 High gain
 GP = 27.0 dB TYP. @ Vcc = 3.0 V
 Low distortion
 OIP₃ = +12.5 dBm TYP. @ Vcc = 3.0 V

High-density surface mounting : 8-pin lead-less minimold package (2.0 × 2.2 × 0.5 mm)

· High performance with minimum external components

• Output matched to 50 Ω

APPLICATION

· Low noise amplifier for GPS and mobile communications

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPC8215TU-E2	μPC8215TU-E2-A	8-pin lead-less minimold (Pb-Free) ^{Note}	8215	 8 mm wide embossed taping Pin 5, 6, 7, 8 indicates pull-out direction of tape Qty 5 kpcs/reel

Note With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

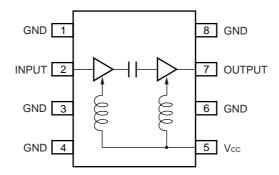
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: µPC8215TU

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Parameter	ameter Symbol Test Conditions			Ratings	Unit
Supply Voltage	Vcc	TA = +25°C		4.0	V
Power Dissipation of Package	Pp	T _A = +85°C	Note	1.06	W
Operating Ambient Temperature	TA			-40 to +85	°C
Storage Temperature	Tstg			–55 to +150	°C
Input Power	Pin			+10	dBm

Note Mounted on double-side copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

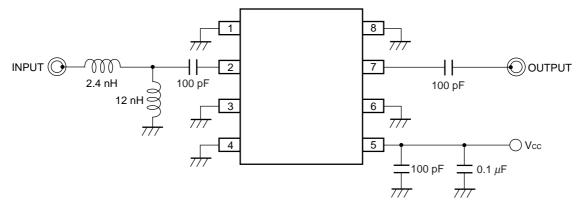
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	2.7	3.0	3.3	٧
Operating Ambient Temperature	TA	-25	+25	+85	°C
Operating Frequency Range	fin	-	1 575	-	MHz

ELECTRICAL CHARACTERISTICS

(TA = +25°C, Vcc = 3.0 V, fin = 1 575 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	Icc	No Signal	I	10.0	13.0	mA
Power Gain	G₽		24.0	27.0	30.0	dB
Noise Figure	NF		I	1.3	1.5	dB
Output 3rd Order Distortion Intercept Point	OIP ₃		I	+12.5	İ	dBm
Input Return Loss	RLin		6.0	7.0	-	dB
Output Return Loss	RLout		10	14.0	-	dB
Isolation	ISL		30	40.0	1	dB
Gain 1 dB Compression Output Power	Po (1 dB)		-	+5.0	-	dBm

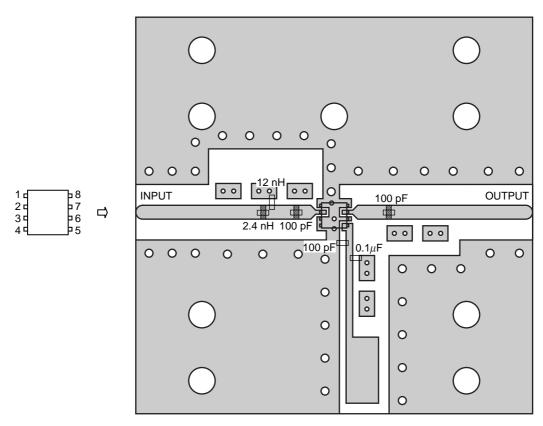
TEST CIRCUIT



Notes

- 1. High performance with minimum external components.
- 2. Output matched to 50 Ω .

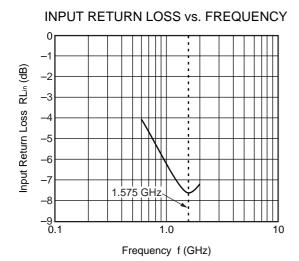
ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

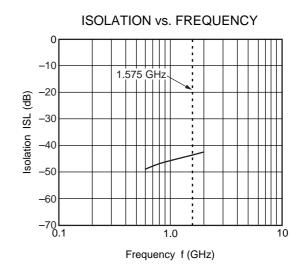


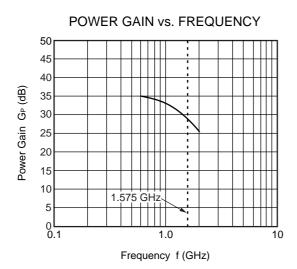
Notes

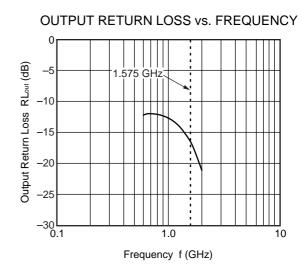
- 1. 30 \times 30 \times 0.51 mm double sided copper-clad hydrocarbon ceramic woven glass PWB (Rogers : R04003, ϵr = 3.38).
- 2. Au plated on pattern
- 3. 12 nH/2.4 nH: Murata LQP15M
- 4. 100 pF/0.1 μ F : Murata GRM15
- 5. represents cutout
- 6. oO: Through holes

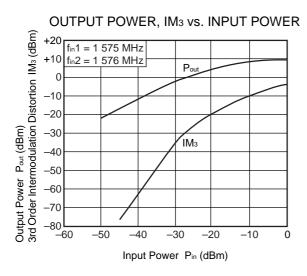
TYPICAL CHARACTERISTICS (Ta = +25°C, Vcc = 3.0 V, unless otherwise specified)







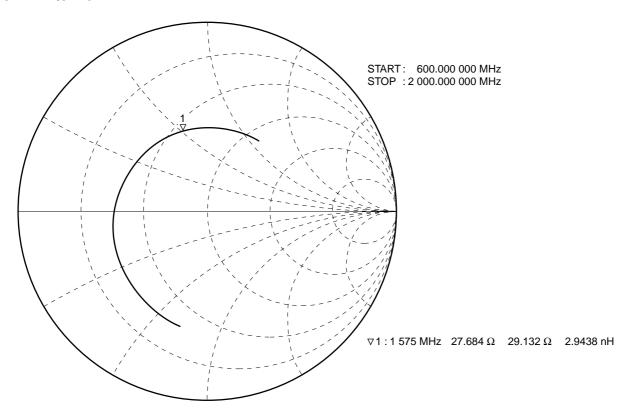




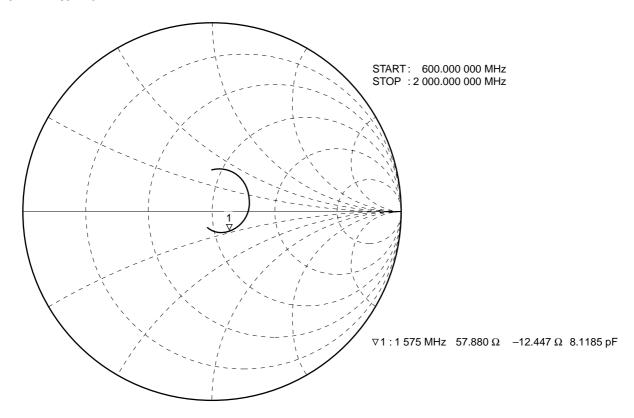
Remark The graphs indicate nominal characteristics.

S-PARAMETERS (Ta = +25°C, Vcc = 3.0 V, monitored at connector on board)

S₁₁-FREQUENCY

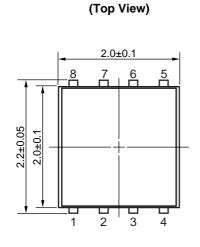


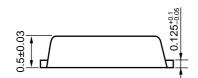
S₂₂-FREQUENCY

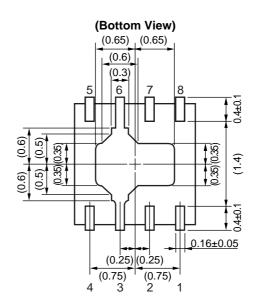


PACKAGE DIMENSIONS

8-PIN LEAD-LESS MINIMOLD (UNIT: mm)







Remark (): Reference value

NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).
 All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration in CEL	on contained devices	
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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